Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A movable microstructure comprising:

a first tiltable assembly formed over a substrate;

a second tiltable assembly formed over the substrate; and

first and second electrodes respectively positioned relative to the substrate to tilt the first and second tiltable assemblies upon activation such that the first and second tiltable assemblies become interdigitated **and substantially coplanar**.

2. (Original) The microstructure recited in claim 1 wherein the first tiltable assembly is configured as a cantilever arrangement.

3. (Original) The microstructure recited in claim 2 wherein the second tiltable assembly is configured as a torsion-beam arrangement.

4. (Original) The microstructure recited in claim 1 wherein the second tiltable assembly is configured as a torsion-beam arrangement.

5. (Cancelled)

6. (Previously Presented) The microstructure recited in claim 1,

wherein the first tiltable assembly includes:

a first structural linkage formed over the substrate;

a first structural film supported by the first structural linkage and having a plurality of fingers at an end of the first structural film; and

wherein the second tiltable assembly includes:

a second structural linkage formed over the substrate; and

a second structural film supported by the second structural linkage and having a plurality of fingers at an end of the second structural film.

7. (Original) The microstructure recited in claim 6 wherein the first and second electrodes comprise polysilicon.

8. (Original) The microstructure recited in claim 6 wherein the first and second structural films comprise polysilicon.

9. (Original) The microstructure recited in claim 6 wherein the first structural linkage has a greater height above the substrate than the second structural linkage.

10. (Currently Amended) A method for fabricating a movable microstructure, the method comprising:

forming a first tiltable assembly over a substrate;

forming a second tiltable assembly over the substrate; and

forming first and second electrodes relative to the substrate to tilt the first and second tiltable assemblies upon activation such that the first and second tiltable assemblies become interdigitated **and substantially coplanar**.

11. (Original) The method recited in claim 10 wherein forming the first tiltable assembly comprises creating a cantilever arrangement.

12. (Original) The method recited in claim 11 wherein forming the second tiltable assembly comprises creating a torsion-beam arrangement.

13. (Original) The method recited in claim 10 wherein forming the second tiltable assembly comprises creating a torsion-beam arrangement.

14. (Cancelled)

15. (Previously Presented) The method recited in claim 10,

wherein forming the first tiltable assembly includes:

forming a first structural linkage over the substrate;

forming a first structural film on the first structural linkage, the first structural film having a plurality of fingers at an end of the first structural film; and

wherein forming the second tiltable assembly includes:

forming a second structural linkage over the substrate; and

forming a second structural film on the second structural linkage, the second structural film having a plurality of fingers at an end of the second structural film.

16. (Previously Presented) The method recited in claim 15 wherein forming the first structural linkage comprises forming the first structural linkage over the substrate at a height greater than the second structural linkage.

17-22. (Cancelled)

23. (Currently Amended) A movable microstructure, the microstructure comprising:

first tiltable means formed over a support means;

second tiltable means formed over the support means; and

means for generating electrostatic forces for tilting the first tiltable means and the second tiltable means into an interdigitated **and substantially coplanar** configuration.

24. (Previously presented) The microstructure recited in claim 23 wherein the first tiltable means comprises cantilever means.

25. (Previously presented) The microstructure recited in claim 24 wherein the second tiltable means comprises torsion-beam means.

26. (Previously presented) The microstructure recited in claim 23 wherein the second tiltable means comprises torsion-beam means.

27-29. (Cancelled)